

Notification# 20181022000.0
Datasheet for LM5008, LM5008A
Information Only

Date: October 24, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services



Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM5008AMM/NOPB	null
LM5008MM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20181022000.0	PCN Date:	October 24, 2018
Title:	Datasheet for LM5008, LM5008A		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		LM5008 <small>SNVS280I – APRIL 2004 – REVISED OCTOBER 2018</small>	
Changes from Revision H (December 2016) to Revision I			
			Page
•	Added links for WEBENCH		1
•	Changed VSSOP-8 body size to 3 mm × 3 mm in <i>Device Information</i>		1
•	Changed <i>Layout Guidelines</i>		17
		LM5008A <small>SNVS583H – MARCH 2009 – REVISED OCTOBER 2018</small>	
Changes from Revision G (December 2016) to Revision H			
			Page
•	Added links for WEBENCH		1
•	Changed VSSOP-8 body size to 3 mm × 3 mm in <i>Device Information</i>		1
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
LM5008	SNVS280H	SNVS280I	
LM5008A	SNVS583G	SNVS583H	
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/LM5008			
http://www.ti.com/product/LM5008A			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
LM5008MM	LM5008MM/NOPB	LM5008MMX	LM5008MMX/NOPB
LM5008AMM/NOPB	LM5008AMMX/NOPB		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com